

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	HAO-JAN PEI	11/25/2019
	CHING-HUA HSIEH	11/25/2019
	HSIU-JEN LIN	11/25/2019
	WEI-YU CHEN	11/25/2019
	CHIA-SHEN CHENG	11/26/2019
	CHIH-CHIANG TSAO	11/29/2019
	JEN-JUI YU	11/26/2019
	CHENG-SHIUAN WONG	11/27/2019
RECEIVING PARTY DATA		
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State/Country:	TAIWAN	
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PROPERTY NUMBERS Total: 1		
	Property Type	Number
	Application Number:	16719984
CORRESPONDENCE DATA		
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NAME OF SUBMITTER:	BELINDA LEE	
SIGNATURE:	/Belinda Lee/	

DATE SIGNED:	12/19/2019
Total Attachments: 4 source=090178_dcl_assgn#page1.tif source=090178_dcl_assgn#page2.tif source=090178_dcl_assgn#page3.tif source=090178_dcl_assgn#page4.tif	

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**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

☒ Declaration Submitted With Initial Filing

OR

☐ Declaration Submitted After Initial Filing (surcharge 37 CFR 1.16(f) required)

(Title of the Invention)

PACKAGE STRUCTURE AND METHOD OF FABRICATING THE SAME

As a below named inventor (hereinafter designated as the undersigned), I hereby
declare that:

This declaration is directed to:

☒ The attached application,

OR

☐ United States Application Number or PCT International application number

_____ Filed on _____

The above-identified application was made or authorized to be made by me.

I believe I am the original inventor or an original joint inventor of a claimed invention in
the application.

The undersigned hereby acknowledge that any willful false statement made in this
declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more
than five (5) years, or both.

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**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

WHEREAS, the undersigned has invented certain new and useful improvements described in the application identified.

WHEREAS, 1. Taiwan Semiconductor Manufacturing Co., Ltd.
of No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78,
R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring the undersigned's interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by the undersigned, the undersigned has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said the undersigned had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

The undersigned further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

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**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

Signature: Pei-Hao Jan Date: 2019.11.25

Legal Name of Sole or First Inventor: **Hao-Jan Pei**

Residence: Hsinchu, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: Ching-Hua Hsieh Date: 2019.11.25

Legal Name of Additional Joint Inventor, if any: **Ching-Hua Hsieh**

Residence: Hsinchu, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: Hsiu-Jen Lin Date: 2019.11.25

Legal Name of Additional Joint Inventor, if any: **Hsiu-Jen Lin**

Residence: Hsinchu County, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: Wei-Yu Chen Date: 2019.11.25

Legal Name of Additional Joint Inventor, if any: **Wei-Yu Chen**

Residence: Taipei City, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: Chia-Shen Cheng Date: 2019.11.26

Legal Name of Additional Joint Inventor, if any: **Chia-Shen Cheng**

Residence: Hsinchu County, Taiwan

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**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

Signature: Chih-Chiang Tsao Date: 2019.11.29

Legal Name of Additional Joint Inventor, if any: **Chih-Chiang Tsao**

Residence: Taoyuan City, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: Jen-Jui Yu Date: 2019.11.26

Legal Name of Additional Joint Inventor, if any: **Jen-Jui Yu**

Residence: Taipei City, Taiwan

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Signature: Cheng-Shiuan Wong Date: 2019.11.29

Legal Name of Additional Joint Inventor, if any: **Cheng-Shiuan Wong**

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